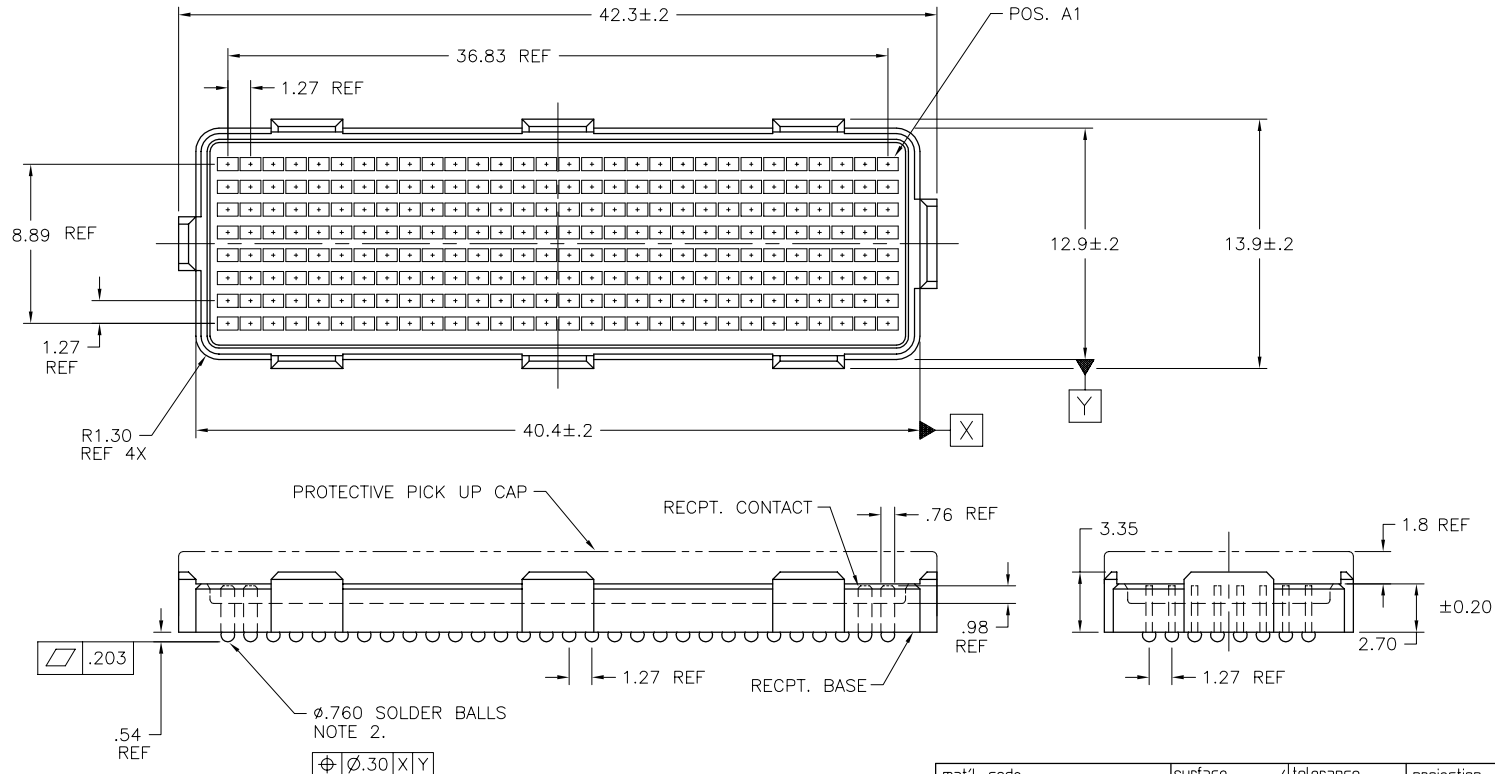
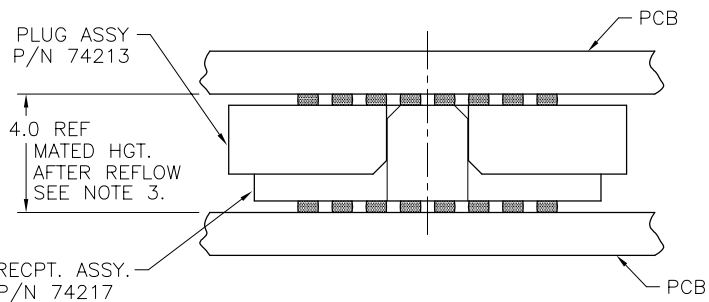
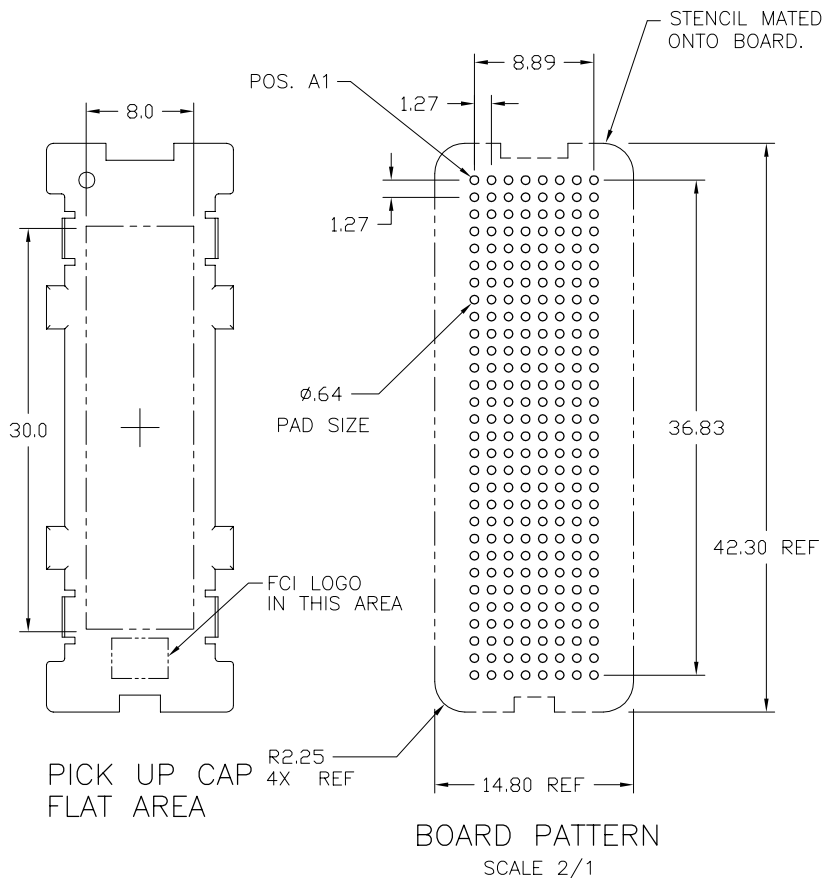


PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
74217-001	YES	15u" (.38um) Au OVER Ni	SnPb
74217-001LF			SnAgCu LEAD FREE (5)(6)
74217-101	YES	30u" (.76um) Au OVER Ni	SnPb
74217-101LF			SnAgCu LEAD FREE (5)(6)
74217-201	YES	SEE NOTE 4.	SnPb
74217-201LF			SnAgCu LEAD FREE (5)(6)

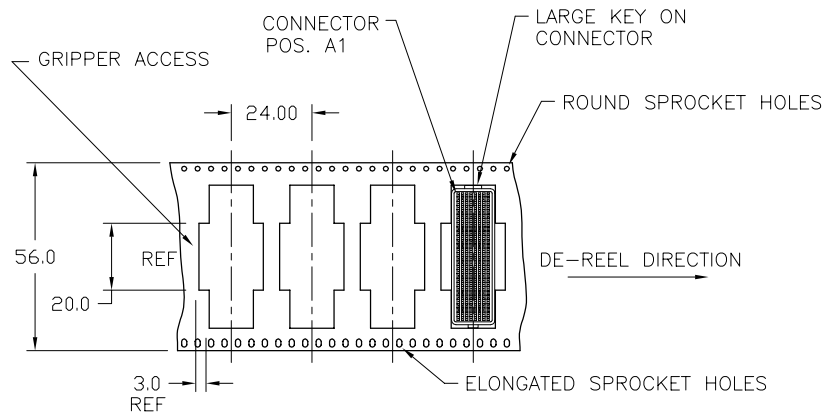


mat'l. code SEE NOTE 1		surface ASME Y14.5 ✓		tolerance ASME Y14.5		projection MM		product family MEG-Array	
ltr	ec'n no	dr	date	tolerances unless otherwise specified		title		title	
M	V06-0560	LP	2006/06/22	angles	.X *3	8 X 30 = 240 POS.		sheet 1 of 3	
-	-	-	-	flat	XX *10	scale 1:1		size A4	
G	V01407	DRW	9/12/00	0° ±2'	XXX *050	FCI		84217	
H	V20006	DRW	1/3/02	dr	D.WAUGHEN	11.12.97		type CUSTOMER Drawing	
J	V20268	DAI	08/23/02	enfr	T.LEMKE	11.12.97			
K	V03-0679	DAI	06/19/03	chr	T.LEMKE	11.12.97			
L	V04-0940	VS	10/18/04	appd	T.LEMKE	11.12.97			
sheet index	revision sheet	M	M	M					
		1	2	3					



MATED HEIGHT AFTER REFLOW IS BASED ON Ø .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS



TAPE & REEL PACKAGING SCALE NONE PER EIA 481-3

mat'l. code SEE NOTE 1		surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection ⊕	product family MEG-Array
ltr	ecr no	dr	date	tolerances unless otherwise specified	title
M				angles X ±3 XX ±10 XXX ±050	4mm RECT. ASSY 8 X 30 = 240POS.
				0° ±2'	scale 1:1
		dr	D.WAUGHEN	11.12.97	dwg no 74217 sheet 2 of 3 size A4 type CUSTOMER Drawing
		enr	T.LEMKE	11.12.97	
		chr	T.LEMKE	11.12.97	
		appd	T.LEMKE	11.12.97	
sheet index	revision sheet				

NOTES:

①. MAT'L:

HOUSING: LCP

CONTACT: COPPER ALLOY

PLATING

CONTACT: (SEE TABLE ON SHEET1)
 SOLDER BALL: (SEE TABLE ON SHEET1)
 EUTECTIC SnPb OR LEAD FREE
 95.5Sn/4Ag/0.5Cu

- ②. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- ③. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- ④. PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
- ⑤. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- ⑥. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

mat'l code SEE NOTE 1		surface ASME Y14.5 ✓		tolerance ASME Y14.5		projection 		product family MEG-Array			
ltr	ecn no	dr	date	tolerances unless otherwise specified				title			
M				angles	line fit	X *3	MM	4mm RECP. ASSY 8 X 30 = 240POS.			
				0° ±2'		XX *10					
						XXX *050	scale 1:1				
		dr	D.WAUGHEN	11.12.97	FCJ		dwg no		sheet 3 of 3	size	
		enr	T.LEMKE	11.12.97			74217		A4		
		chr	T.LEMKE	11.12.97							
		appd	T.LEMKE	11.12.97			type		CUSTOMER Drawing		
sheet index	revision sheet										